

N-channel 600 V, 0.260 Ω typ., 12 A MDMesh™ DM2 Power MOSFET in a D²PAK package

Datasheet - production data

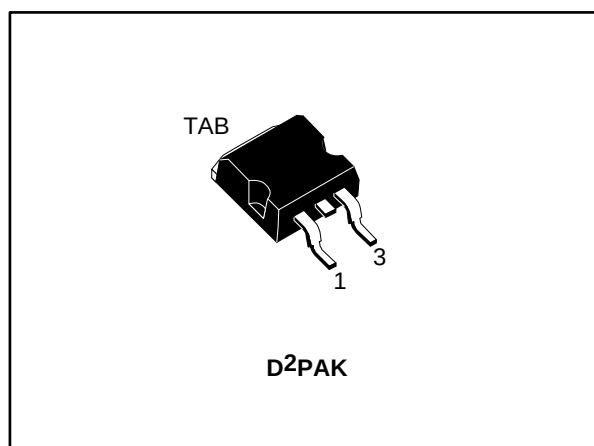
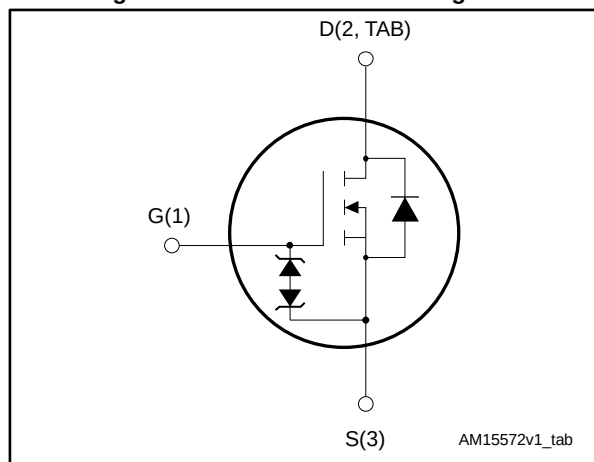


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D
STB18N60DM2	600 V	0.295 Ω	12 A

- Fast-recovery body diode
- Extremely low gate charge and input capacitance
- Low on-resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

Applications

- Switching applications

Description

This high voltage N-channel Power MOSFET is part of the MDMesh™ DM2 fast recovery diode series. It offers very low recovery charge (Q_{rr}) and time (t_{rr}) combined with low $R_{DS(on)}$, rendering it suitable for the most demanding high efficiency converters and ideal for bridge topologies and ZVS phase-shift converters.

Table 1: Device summary

Order code	Marking	Package	Packing
STB18N60DM2	18N60DM2	D ² PAK	Tape and reel

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
	2.1 Electrical characteristics (curves).....	6
3	Test circuits	8
4	Package information	9
	4.1 D ² PAK_(TO-263)_type_A_package information	9
	4.2 D ² PAK packing information	12
5	Revision history	14

1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 25	V
I_D	Drain current (continuous) at $T_{case} = 25\text{ °C}$	12	A
	Drain current (continuous) at $T_{case} = 100\text{ °C}$	7.6	
$I_{DM}^{(1)}$	Drain current (pulsed)	48	A
P_{TOT}	Total dissipation at $T_{case} = 25\text{ °C}$	90	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	40	V/ns
$dv/dt^{(3)}$	MOSFET dv/dt ruggedness	50	
T_{stg}	Storage temperature	-55 to 150	°C
T_j	Maximum junction temperature	150	

Notes:

⁽¹⁾ Pulse width is limited by safe operating area.

⁽²⁾ $I_{SD} \leq 12\text{ A}$, $di/dt \leq 400\text{ A}/\mu\text{S}$, $V_{DS(peak)} < V_{(BR)DSS}$, $V_{DD} = 80\% V_{(BR)DSS}$.

⁽³⁾ $V_{DS} \leq 480\text{ V}$.

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	1.39	°C/W
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	30	

Notes:

⁽¹⁾ When mounted on 1 a inch² FR-4, 2 Oz copper board

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
$I_{AR}^{(1)}$	Avalanche current, repetitive or not repetitive	2.5	A
$E_{AR}^{(2)}$	Single pulse avalanche energy	380	mJ

Notes:

⁽¹⁾ Pulse width is limited by T_{jmax} .

⁽²⁾ starting $T_j = 25\text{ °C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$.

2 Electrical characteristics

($T_{\text{case}} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Table 5: Static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{\text{GS}} = 0\text{ V}$, $I_{\text{D}} = 1\text{ mA}$	600			V
I_{DSS}	Zero gate voltage drain current	$V_{\text{GS}} = 0\text{ V}$, $V_{\text{DS}} = 600\text{ V}$			1.5	μA
		$V_{\text{GS}} = 0\text{ V}$, $V_{\text{DS}} = 600\text{ V}$, $T_{\text{case}} = 125\text{ }^{\circ}\text{C}$			100	μA
I_{GSS}	Gate-body leakage current	$V_{\text{DS}} = 0\text{ V}$, $V_{\text{GS}} = \pm 25\text{ V}$			± 10	μA
$V_{\text{GS(th)}}$	Gate threshold voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_{\text{D}} = 250\text{ }\mu\text{A}$	3	4	5	V
$R_{\text{DS(on)}}$	Static drain-source on-resistance	$V_{\text{GS}} = 10\text{ V}$, $I_{\text{D}} = 6\text{ A}$		0.260	0.295	Ω

Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{\text{DS}} = 100\text{ V}$, $f = 1\text{ MHz}$, $V_{\text{GS}} = 0\text{ V}$	-	800	-	pF
C_{oss}	Output capacitance		-	40	-	
C_{rss}	Reverse transfer capacitance		-	1.33	-	
$C_{\text{oss eq.}}^{(1)}$	Equivalent output capacitance	$V_{\text{DS}} = 0\text{ to }480\text{ V}$, $f = 1\text{ MHz}$, $V_{\text{GS}} = 0\text{ V}$	-	80	-	pF
R_{G}	Intrinsic gate resistance	$f = 1\text{ MHz}$, $I_{\text{D}} = 0\text{ A}$	-	5.6	-	Ω
Q_{g}	Total gate charge	$V_{\text{DD}} = 480\text{ V}$, $I_{\text{D}} = 12\text{ A}$, $V_{\text{GS}} = 10\text{ V}$ (see Figure 14: "Gate charge test circuit")	-	20	-	nC
Q_{gs}	Gate-source charge		-	5.2	-	
Q_{gd}	Gate-drain charge		-	8.5	-	

Notes:

⁽¹⁾ $C_{\text{oss eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{\text{d(on)}}$	Turn-on delay time	$V_{\text{DD}} = 300\text{ V}$, $I_{\text{D}} = 6\text{ A}$ $R_{\text{G}} = 4.7\text{ }\Omega$, $V_{\text{GS}} = 10\text{ V}$ (see Figure 13: "Switching times test circuit for resistive load" and Figure 18: "Switching time waveform")	-	13.5	-	ns
t_{r}	Rise time		-	8	-	
$t_{\text{d(off)}}$	Turn-off-delay time		-	9.5	-	
t_{f}	Fall time		-	32.5	-	

Table 8: Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		12	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		48	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0\text{ V}$, $I_{SD} = 12\text{ A}$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 12\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$ (see Figure 15: "Test circuit for inductive load switching and diode recovery times")	-	125		ns
Q_{rr}	Reverse recovery charge		-	0.675		nC
I_{RRM}	Reverse recovery current		-	11		A
t_{rr}	Reverse recovery time	$I_{SD} = 12\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$, $T_j = 150\text{ °C}$ (see Figure 15: "Test circuit for inductive load switching and diode recovery times")	-	190		ns
Q_{rr}	Reverse recovery charge		-	1225		nC
I_{RRM}	Reverse recovery current		-	13		A

Notes:

⁽¹⁾ Pulse width is limited by safe operating area.

⁽²⁾ Pulse test: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics (curves)

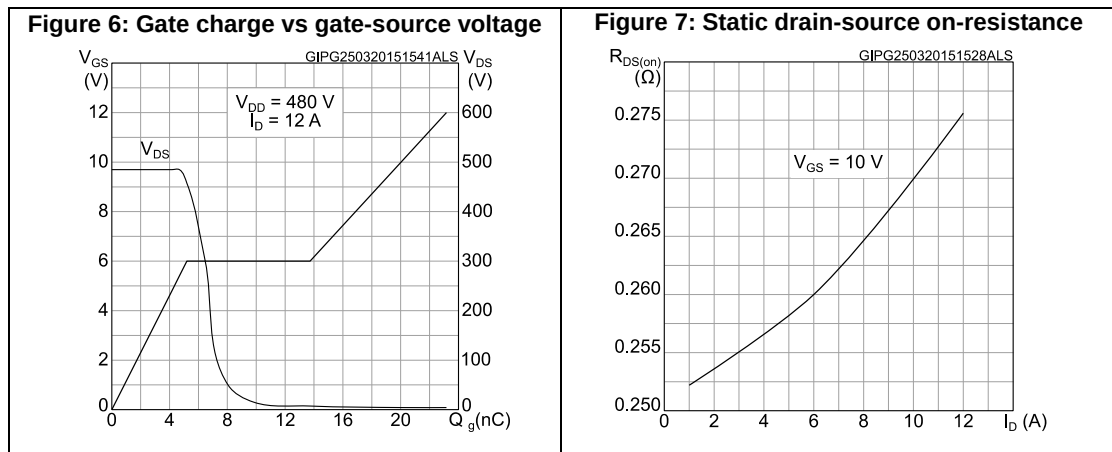
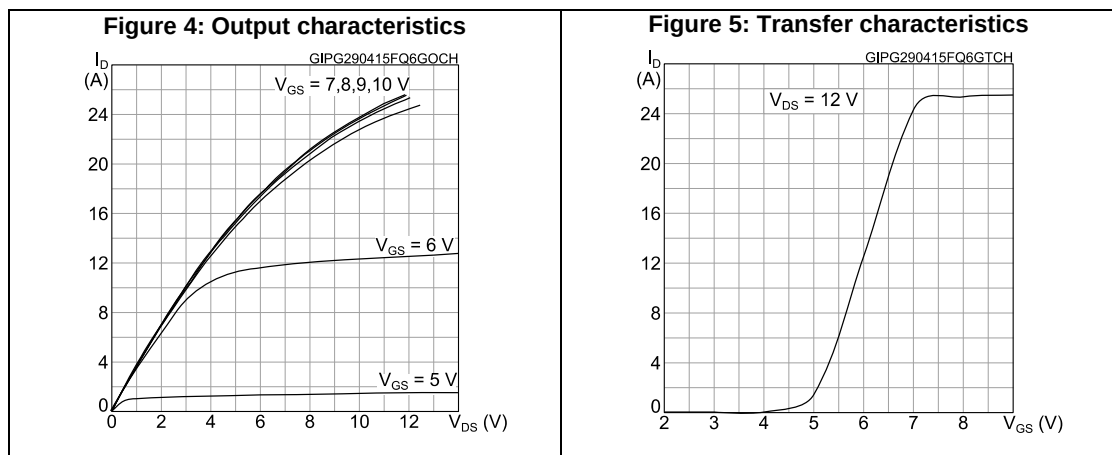
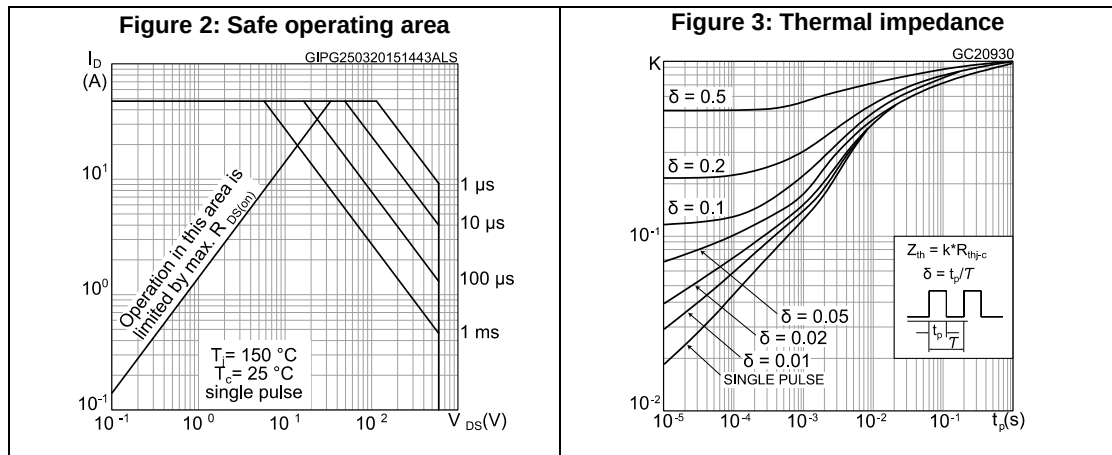


Figure 8: Capacitance variations

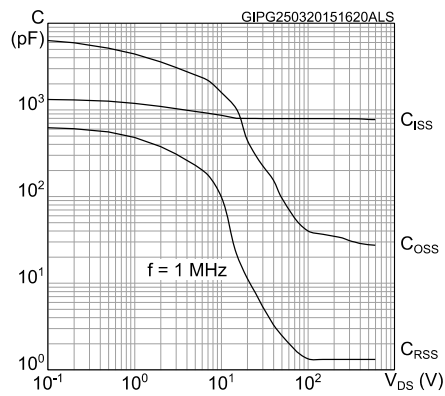


Figure 9: Normalized gate threshold voltage vs temperature

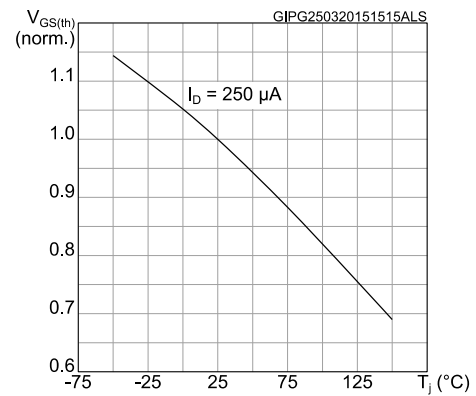


Figure 10: Normalized on-resistance vs temperature

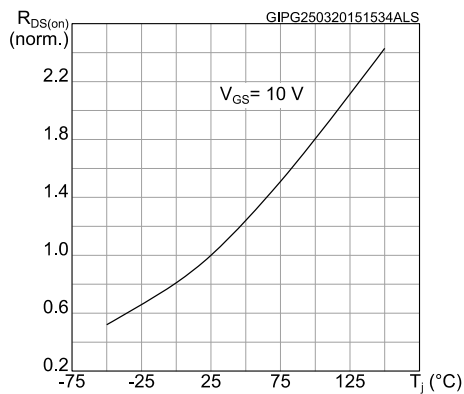
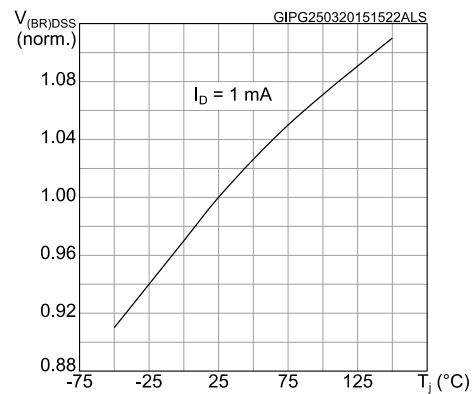
Figure 11: Normalized $V_{(BR)DSS}$ vs temperature

Figure 12: Source-drain diode forward characteristics

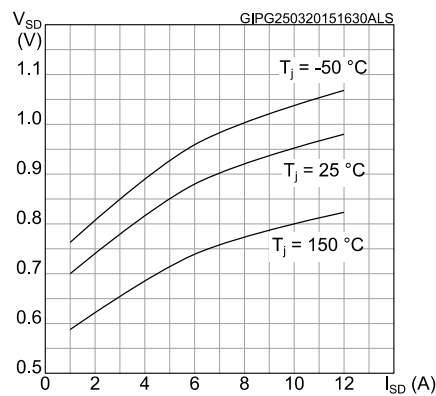


Figure 13: Switching times test circuit for resistive load

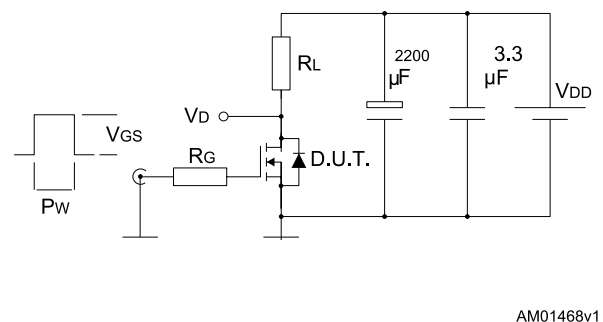


Figure 14: Gate charge test circuit

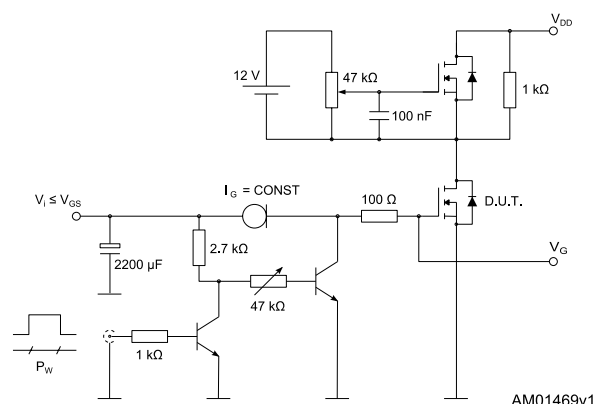


Figure 15: Test circuit for inductive load switching and diode recovery times

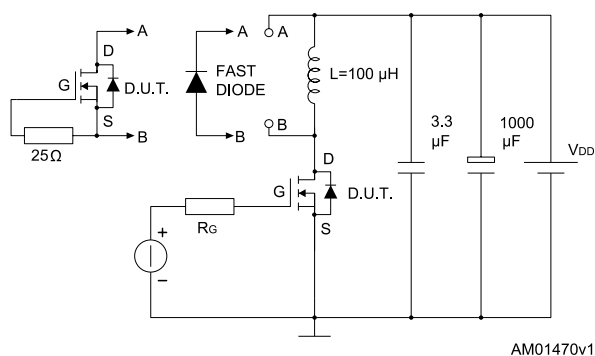


Figure 16: Unclamped inductive load test circuit

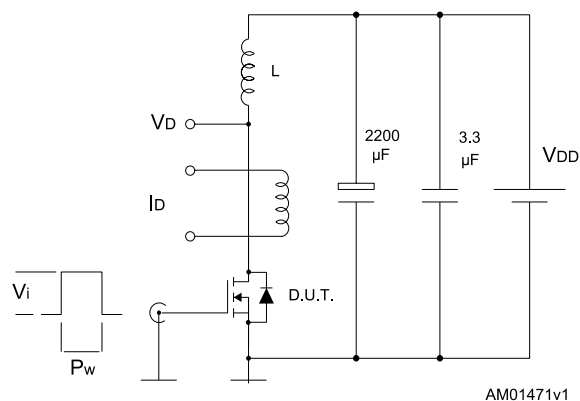


Figure 17: Unclamped inductive waveform

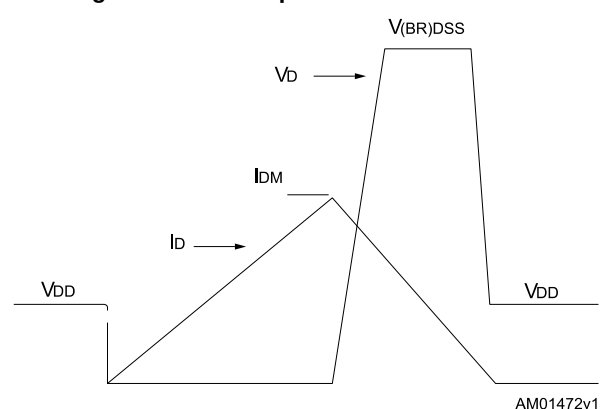
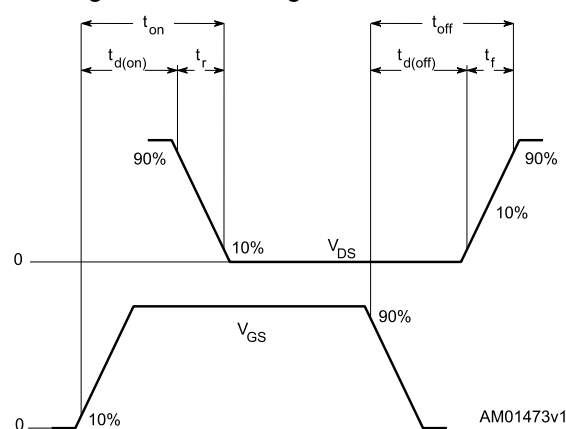


Figure 18: Switching time waveform

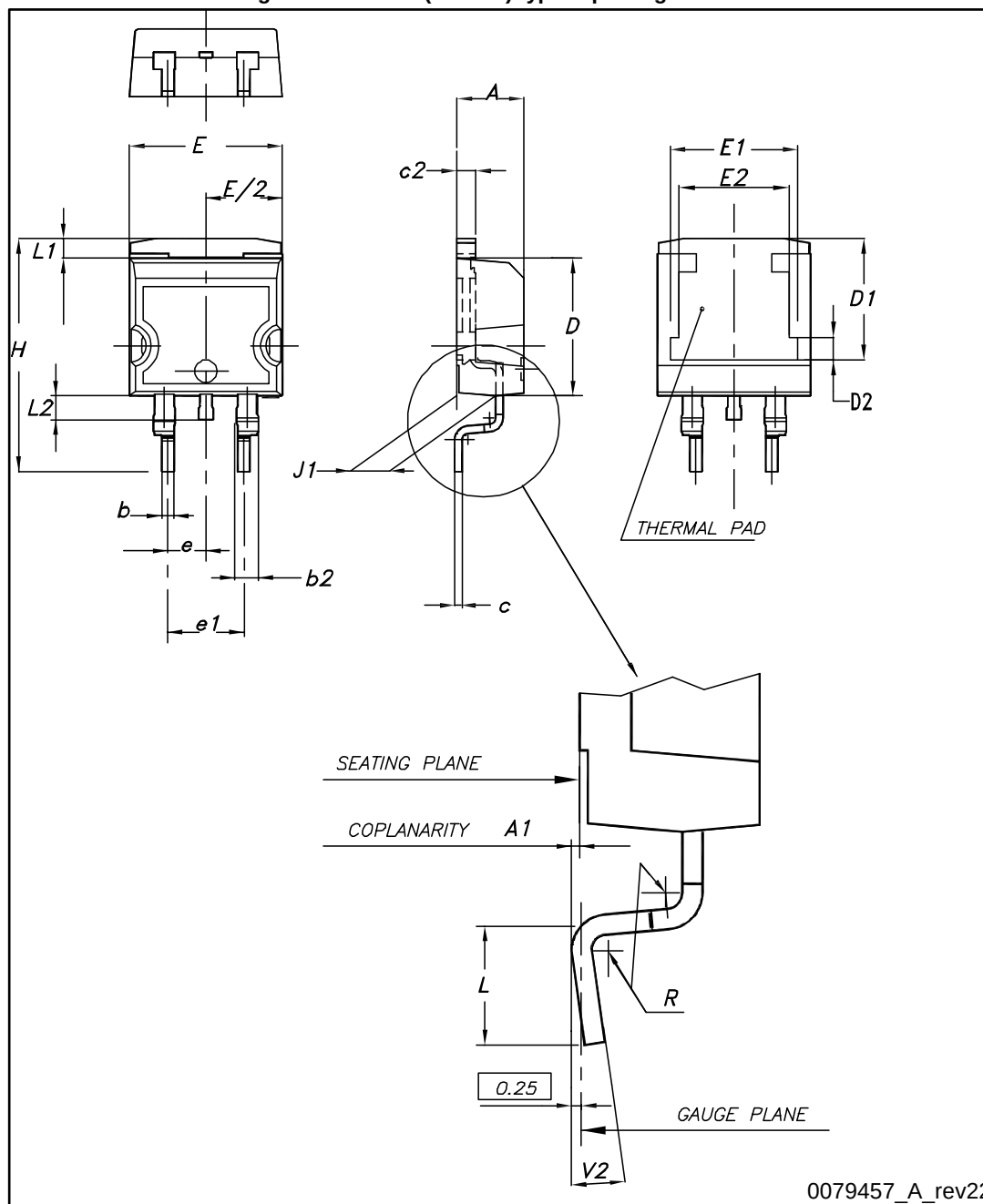


4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 D²PAK_(TO-263)_type_A package information

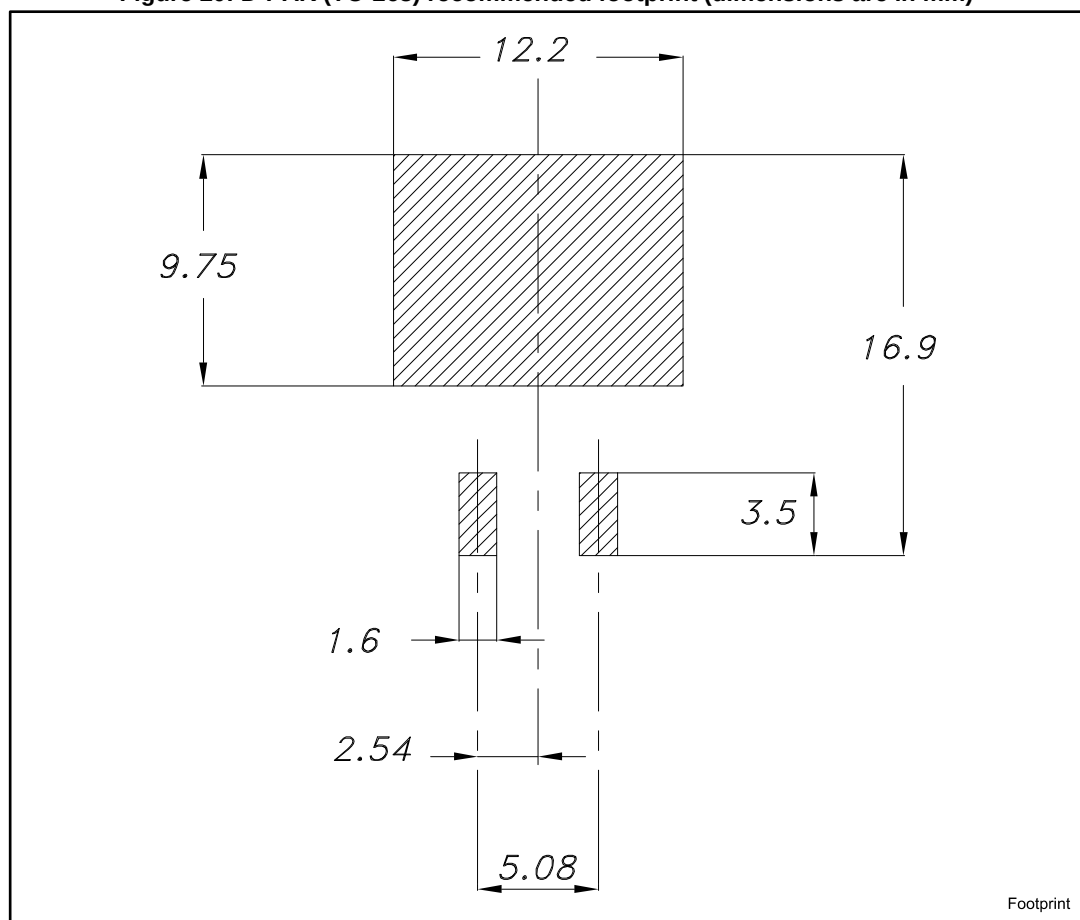
Figure 19: D²PAK (TO-263) type A package outline



0079457_A_rev22

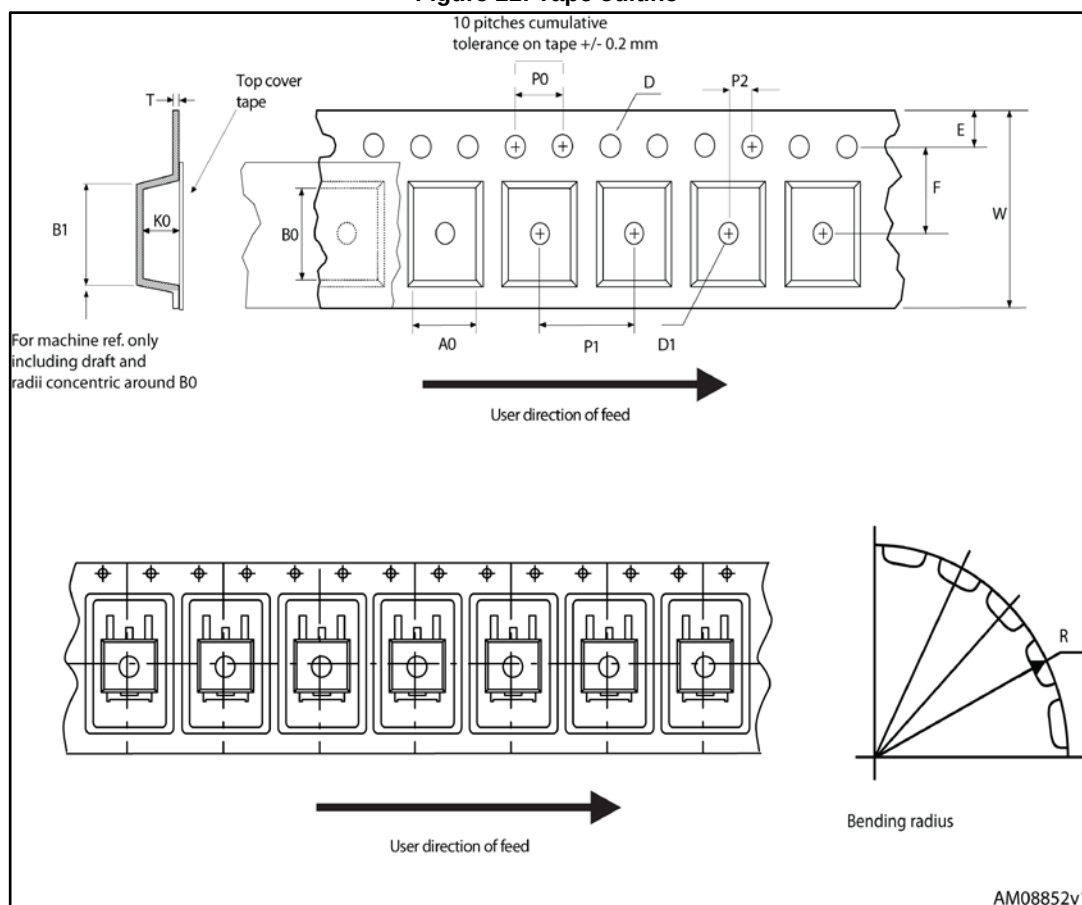
Table 9: D²PAK (TO-263) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10		10.40
E1	8.50	8.70	8.90
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

Figure 20: D²PAK (TO-263) recommended footprint (dimensions are in mm)

4.2 D²PAK packing information

Figure 21: Tape outline



Technical drawing of a tape reel showing front and side views with dimensions A through T.

Front View Dimensions:

- A:** Overall diameter of the reel.
- B:** Diameter of the central hub.
- C:** Diameter of the tape slot.
- D:** Diameter of the inner core.
- E:** Diameter of the tape slot.
- F:** Diameter of the inner core.
- G:** Diameter of the tape slot.
- H:** Diameter of the inner core.
- I:** Diameter of the tape slot.
- J:** Diameter of the inner core.
- K:** Diameter of the tape slot.
- L:** Diameter of the inner core.
- M:** Diameter of the tape slot.
- N:** Diameter of the inner core.
- O:** Diameter of the tape slot.
- P:** Diameter of the inner core.
- Q:** Diameter of the tape slot.
- R:** Diameter of the inner core.
- S:** Diameter of the tape slot.
- T:** Diameter of the inner core.

Side View Dimensions:

- U:** Thickness of the tape.
- V:** Thickness of the tape.
- W:** Thickness of the tape.
- X:** Thickness of the tape.
- Y:** Thickness of the tape.
- Z:** Thickness of the tape.
- AA:** Thickness of the tape.
- AB:** Thickness of the tape.
- AC:** Thickness of the tape.
- AD:** Thickness of the tape.
- AE:** Thickness of the tape.
- AF:** Thickness of the tape.
- AG:** Thickness of the tape.
- AH:** Thickness of the tape.
- AI:** Thickness of the tape.
- AJ:** Thickness of the tape.
- AK:** Thickness of the tape.
- AL:** Thickness of the tape.
- AM:** Thickness of the tape.
- AN:** Thickness of the tape.
- AO:** Thickness of the tape.
- AP:** Thickness of the tape.
- AQ:** Thickness of the tape.
- AR:** Thickness of the tape.
- AS:** Thickness of the tape.
- AT:** Thickness of the tape.

Other Labels:

- 40mm min. access hole at slot location:** Points to a small circular hole on the outer edge of the reel.
- Tape slot in core for tape start 2.5mm min. width:** Points to the central slot in the inner core.
- Full radius:** Points to the outer edge of the reel.
- G measured at hub:** Points to the diameter of the tape slot at the hub.

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base qty		1000
P2	1.9	2.1	Bulk qty		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

5 Revision history

Table 11: Document revision history

Date	Revision	Changes
01-Apr-2015	1	First release.
20-May-2015	2	Text edits and formatting changes throughout document In Section 2.1 Electrical characteristics (curves): - updated Figure 4: Output characteristics - updated Figure 5: Transfer characteristics

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2015 STMicroelectronics – All rights reserved